PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
EFFECTIVE DATE:	01/10/2007	

CONVEYING PARTY DATA

Name	Execution Date
Deepak K. Pai	01/10/2007

RECEIVING PARTY DATA

Name:	General Dynamics Advanced Information Systems, Inc.		
Street Address:	12450 Fair Lakes Circle		
Internal Address: Suite 800			
City:	Fairfax		
State/Country:	State/Country: VIRGINIA		
Postal Code:	22033		

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11496467

CORRESPONDENCE DATA

Fax Number: (202)429-3902

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Phone: 2024293000

Email: swatkins@steptoe.com

Correspondent Name: Scott D. Watkins

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Address Line 2: Steptoe & Johnson LLP

Address Line 4: Washington, DISTRICT OF COLUMBIA 20036

NAME OF SUBMITTER: Scott/D/Watkins

Total Attachments: 1

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PATENT REEL: 018752 FRAME: 0809

500206681

Attorney Docket: 12492.0264

ASSIGNMENT

WHEREAS, I, Deepak K. Pai, a citizen of the United States of America, residing at 11516 22nd Avenue – S, Burnsville, Minnesota 55337, ASSIGNOR, am the inventor of the invention in METHOD AND APPARATUS FOR COMPLIANTLY CONNECTING A STACK OF HIGH-DENSITY ELECTRONIC MODULES IN HARSH ENVIRONMENTS

[X] which bears Serial No. 11/496,467, and was filed on August 1, 2006, and

WHEREAS, General Dynamics Advanced Information Systems, Inc., organized and existing under the laws of the United States and having a place of business at 12450 Fair Lakes Circle, Suite 800, Fairfax, Virginia 22033, ASSIGNEE, is desirous of obtaining my entire right, title and interest in, to and under the said invention and the said application:

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) to me in hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, I, the said ASSIGNOR, have soid, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, my entire right, titic and interest in, to and under the said invention, and the said United States provisional application and all applications claiming priority thereto under 35 U.S.C. §119(e) and divisions, renewals and continuations thereof, and all Patents of the United States which may be granted thereon and all reissues and extensions thereof; and all applications for industrial property protection, including, without limitation, all applications for patents, utility models, and designs which may hereafter be filed for said invention in any country or countries foreign to the United States, together with the right to file such applications and the right to claim for the same the priority rights derived from said United States application under the Patent Laws of the United States, the International Convention for the Protection of Industrial Property, or any other international agreement or the domestic laws of the country in which any such application is filed, as may be applicable; and all forms of industrial property protection, including, without limitation, patents, utility models, inventors' certificates and designs which may be granted for said invention in any country or countries foreign to the United States and all extensions, renewals and reissues thereof; and

I HEREBY authorize and request the Commissioner of Patents and Trademarks of the United States, and any official of any country or countries foreign to the United States, whose duty it is to issue patents or other evidence or forms of industrial property protection on applications as aforesaid, to issue the same to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument; and

I HEREBY covenant and agree that I have full right to convey the entire interest herein assigned, and that I have not executed, and will not execute, any agreement in conflict herewith; and

I HEREBY further covenant and agree that I will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known to me respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing, reissue and foreign applications, make all rightful oaths, and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper protection for said invention in all countries.

IN TESTIMONY WHEREOF, I hereunto set my hand and seal the day and year set opposite my signature.

Date	JAHUARY	10	, 2007	Deepakke. Pai
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Page 1 of 1

RECORDED: 01/12/2007

PATENT REEL: 018752 FRAME: 0810